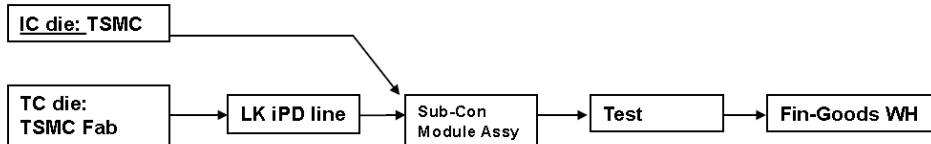


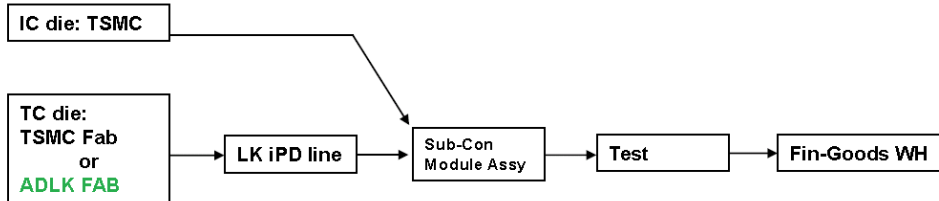
PCN 13_0109:

Alternate fab source for ISO TC start silicon die.
To enable additional wafer fabrication capacity.

Current Flow:



Alternate Flow:



QUALIFICATION PLAN# 10558			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	1 x 77	Passed
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	1 x 77	Passed
Autoclave	JEDEC <i>JESD22-A102</i>	1 x 77	Passed
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	1 x 77	Passed
Early Life Failure (ELF)	MIL-STD-883 <i>Method 1015</i>	3 x 667	Passed
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45	Passed
Solder Heat Resistance (SHR)*	<i>ADI-0049</i>	1 x 30	Passed
Latch-Up	JEDEC <i>JESD78</i>	6	Passed
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	3/voltage	Passed Passed Passed
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Passed Passed Passed
Electrostatic Discharge <i>Machine Model</i>	JEDEC <i>JESD22-A115</i>	3/voltage	Passed Passed Passed

*Preconditioned per JEDEC/IPC J-STD-020